

Outsourced Semiconductor Assembly and Test Market (OSAT) Trends: Market Research Report

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Abstracts

The Outsourced Semiconductor Assembly and Test Services market is projected to witness significant upsurge, primarily driven by the increase in packaging costs and a rapid transformation towards the adoption of outsourcing model in the coming years.

The report analyzes and presents an overview of Outsourced Semiconductor Assembly and Test market worldwide. The report in addition provides global market estimates and projections in US dollars for Outsourced Semiconductor Assembly and Test (OSAT) for years 2012 through 2017. Supported with 2 market data tables, the report provides a review of market trends, growth drivers, and various strategic industry activities of major companies witnessed by the industry over the last few years. In addition, 37 companies operating in the Outsourced Semiconductor Assembly and Test market worldwide including Amkor Technology, BE Semiconductor Industries, Cirtek Electronics Corporation, Denis Ferranti Group, IBM Microelectronics, PSI Technologies, STATS ChipPAC, Toshiba Semiconductor & Storage Products Company, Unisem (M) Bhd, and others are profiled.

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Back-end Manufacturing Processes Provide Impetus to Outsourced Semiconductor Assembly and Test Companies

Major Growth Drivers

Increased Adoption of Packaging and Assembly Technologies in Diversified Electronic and Portable Devices

Rapid Expansion of Outsourced Semiconductor Assembly and Test Companies in Southeast Asia

Electronic Outsourcing Services Industry Fails to Address Demand of Middle Market

Japanese Chipmakers Turn towards Outsourcing of Assembly & Test Processes

2. RECENT INDUSTRY ACTIVITY

Amkor Signs MoU with Toshiba to Take Over Toshiba Electronics Malaysia

ASE Assembly & Test (Shanghai) to Take Over Wuxi Tongzhi Microelectronics

Renesas Electronics Inks MoU with J-Devices

STATS ChipPAC and UMC Microelectronics Introduce Advanced 3D IC Chip Stacking Technology

Shinko Electric Industries Obtains License to Use TMV Technology of Amkor Technology

Salland Engineering International and Pintail Technologies Merge

Dynamic Test Solutions and Tessolve Services Sign Merger Agreement

3. MARKET PARTICIPANTS

Advanced Semiconductor Engineering, Inc. (Taiwan)
Amkor Technology, Inc. (USA)
Ardentec Corp. (Taiwan)
ASE Assembly & Test (Shanghai) Ltd. (China)
Automated Technology (Phil), Inc. (Philippines)
BE Semiconductor Industries N. V. (The Netherlands)
Carsem (M) Sdn. Bhd. (Malaysia)
ChipMOS Technologies (Bermuda) LTD. (Taiwan)
Cirtek Electronics Corporation (Philippines)
Denis Ferranti Group (UK)
Dynamic Test Solutions Asia Pte. , Ltd. (Singapore)
EEMS Italia SpA (Italy)
GEM Services, Inc. (China)
IBM Microelectronics (USA)
J-DEVICES Corporation (Japan)
King Yuan Electronics Co. , Ltd. (Taiwan)
Kulicke & Soffa Industries, Inc. (Singapore)
Lingsen Precision Industries, Ltd. (Taiwan)
LTX-Credence Corporation (USA)
Orient Semiconductor Electronics (Taiwan)
Powertech Technology, Inc. (Taiwan)
PSI Technologies, Inc. (Philippines)
Salland Engineering International (The Netherlands)
Signetics Corporation (Korea)
Siliconware Precision Industries Co. , Ltd. (Taiwan)
SPEL Semiconductor Ltd. (India)
Stars Microelectronics (Thailand) Public Company Ltd. (Thailand)
STATS ChipPAC, Ltd. (Singapore)
Tektronix Component Solutions (USA)
Tessolve Services Pvt. Ltd. (India)
Tianshui Huatian Microelectronics Co. , Ltd. (China)
Tong Hsing Electronic Industries Ltd. (Taiwan)
Toshiba Semiconductor & Storage Products Company (Japan)
Unisem (M) Bhd. (Malaysia)
United Microelectronics Corporation (Taiwan)
United Test and Assembly Center Ltd. (Singapore)
Youngtek Electronics Corporation (YTEC) (Taiwan)

4. APPENDIX

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